	IEEE WMED 2024 Technical Program	
7:15 AM	Check-In, Registration, and Continental Breakfast (Double R Ranch Room)	
	Welcome Address	
8:00am	n Double R Ranch Room	
	Curtis Cahoon, General	Chair, IEEE WMED 2024
	Plenary Session	
	Double R Ranch Room, Session Chair: Jai Jaiprakash, Micron	
8:15am	Meeting Workforce Demands for the AI Revolution Janine Rush-Byers and Shawn Siddoway, Micron Technology	
9:15am	Keynote Talk II: Analog-memory-based In-Memory-Computing Accelerators for Deep Neural Networks Sidney Tsai, IBM	
10:15am	Break	
	Invited Talks: Session 1	
	Track 1	Track 2
	Double R Ranch Room, Session Chair: Tim Hollis and Curtos Cahoon, Micron	Skyline Room, Chair: Kurtis Cantley, Boise State University
10:30am	Application of machine learning techniques to chip design Sunil Sudhakaran, NVIDIA and Stanford University	Spiking Neural Network Design for Neuromorphic Hardware Adarsha Balaji, Argonne National Laboratory
11:15am	Advanced Packaging: A critical enabler for AI Computing needs Bharat Penmecha, Intel	Neuromorphic Computing for Future Al Systems Cory Merkel, Rochester Institute of Technology
12:00pm	Lunch Break (Double R Ranch and Skyline Room)	
12:45pm	Poster Session (Double R Ranch)	
	Invited Talks: Session 2	
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	Double R Ranch Room, Session Chair: Sumeet Pandey, Micron	I FACK 2 Skyline Room, Session Chair: Omiya Hassan, Boise State University
1:30pm	On Digital Twins for Semiconductor Manufacturing Surya Kalidindi, Georgia Tech	I FaCK 2 Skyline Room, Session Chair: Omiya Hassan, Boise State University HBM Technology, an Overview Joe McCrate and Raghu Sreeramaneni, Micron Technology
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*Co-authored Papers, only presenter's name is mentioned. For a complete author and affiliations list, please see the Contributed Papers section of the Program Booklet.